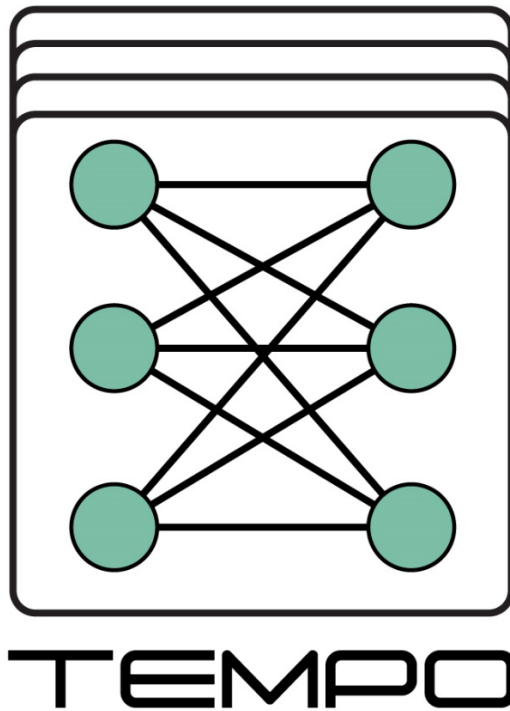


Technology & Hardware for nEuromorphic coMPuting

- ECSEL Research and Innovation Actions (RIA*) -



Deliverable 2.6

- SNN/DNN vs. Technical Specification Table -

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Publishable Summary

This deliverable is a joint report between Infineon AG and Robert Bosch GmbH. The scope is the definition of technical requirements towards emerging memories used as weights in SNNs and DNNs.

Infineon AG has been focused on specifying the requirements for the SNN ASIC, which is developed in the Tempo project by them for consumer applications.

Robert Bosch GmbH has been working on defining the technical specification and requirements for embedded NVMs used in Automotive ASICs w.r.t. Automotive reliability, quality, safety and security requirements. This report summarizes the general requirements and the assessment of MRAM and OxRAM as potential embedded NVM solutions for Automotive ASICs.